PCN Numl	oer:	20	23082	5000	). 1 <mark>A</mark>		PCN	N Da	ite:	September 27, 2023		
Title:	Qualificatio	n of U	MC-F1	2 as	additional Fab	site for	selec	t LE	3C9 de	evices		
Customer	Contact:	Chan	ge Ma	nage	ement team	Dept:		Qua	lity Se	rvices		
Proposed	1 <sup>st</sup> Ship Da	te:	Nov 2	28, 2	2023		Sample requests accepted until:			Oct 27, 2023*		
*Sample r	equests re	ceive	d after	· Oc	tober 27, 202	3 will n	ot be	e sı	ıppor	ted.		
Change Ty	pe:											
Assem	bly Site				Design			Wafer	Bump Material			
Assem	bly Process				Data Sheet				Wafer	Bump Process		
Assem	bly Materials	6			Part number c	hange		X	Wafer	Fab Site		
Mecha	nical Specific	cation			Test Site				Wafer Fab Material			
Packin	g/Shipping/l	abelin	ıg		Test Process				Wafer	Fab Process		
					PCN Detai	ls						

# **Description of Change:**

Revision A is to announce the addition of new devices that were not included in the original PCN notification. The new devices are highlighted in yellow and **bolded** in the product affected section below. For these newly added devices ONLY, the expected first shipment date will be 90 days from the date of this notice, and sample requests will be accepted until 30 days from the date of this notice. The proposed 1<sup>st</sup> ship date of November 28, 2023 still applies for the original set of devices.

Texas Instruments is pleased to announce the qualification of an aUMC-F12 as an additional fab for the selected devices listed in the "Product Affected" section.

С	urrent Fab Site	9	New Fab Site					
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter			
RFAB	LBC9	300 mm	UMC-F12	LBC9	300 mm			

Qual details are provided in the Qual Data Section.

# **Reason for Change:**

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

### **Fab Site Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
UMC-F12	F12	TWN	Tainan

Sample product shipping label (not actual product label)





(1P) SN74LS07NSR (a) 2000 (D) 0336 (31T)LOT: 3959047MLA 4W) TKY(1T) 7523483SI2 (V) 0033317 (21L) CCO:USA (2P) REV: CSO: SHE (22L) ASO: MLA (23L) ACO: MYS

<b>Product Affected:</b>	Product Affected:											
BQ25300RTER	SN2101016RSMR	SN2206024YBGR	TPS51397ARJER									
BQ25302RTER	SN2101017RSMR	SN2206025YBGR	TPS65991BFRSMR									
BQ25303JRTER	SN2101018REFR	SN2206026YBGR	TPS65992DBFREFR									
BQ25306RTER	SN2101020RSMR	SN2206027YBGR	TPS65992SBFRSMR									
SN2101008RSMR	SN2101021RSMR	SN2206029YBGR	TPS65993BHYBGR									
SN2101009RSMR	SN2101022REFR	SN2206030YBGR	TPS65994BHYBGR									
SN2101010REFR	SN2206023YBGR	SN2206031YBGR										

### Qualification Results

### Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: BQ25300RTER	Qual Device: BQ25302RTER	Qual Device: BQ25303JRTER	Qual Device: BQ25306RTER	QBS Package Reference: TPS61378QWRTERQ1	QBS Package Reference: BQ25890HRTWR	QBS Process Reference: CD3253DB0YCHR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	-
UHAST	А3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	-
UHAST	АЗ	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	-
тс	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	3/135/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	3/231/0
ELFR	B2	ELFR	125C	48 Hours	-	-	-	-	-	-	3/3000/0
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	-	-

Туре	#	Test Name	Condition	Duration	Qual Device: BQ25300RTER	Qual Device: BQ25302RTER	Qual Device: BQ25303JRTER	Qual Device: BQ25306RTER	QBS Package Reference: <u>TPS61378QWRTERQ1</u>	QBS Package Reference: BQ25890HRTWR	QBS Process Reference: CD3253DB0YCHR
ESD	E2	ESD CDM		250 Volts	-	-	-	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	1/3/0	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	1/Pass	-	-	-
FTY	E6	Final Test Yield	-	-	1/Pass	1/Pass	1/Pass	1/Pass	-	-	-

- QBS: Qual By Similarity
- Qual Device BQ25300RTER is qualified at MSL2 260C
   Qual Device BQ25302RTER is qualified at MSL1 260C
   Qual Device BQ25303JRTER is qualified at MSL1 260C
- Qual Device BQ25306RTER is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2212-006

# **PCN Rev A Qual Results**

#### **Qualification Results**

### Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	Qual Device: TPS51397ARJER	QBS Process Reference: TPS51486RJER	QBS Product Reference: TPS51393PRJER	QBS Product Reference: TPS51397ARJER	QBS Product, Package, Process Reference: TPS56C230RJER
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	3/231/0	-	-	-
UHAST	А3	Autoclave	121C/15psig	96 Hours	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-55C/125C	1000 Cycles	-	-	-	-	1/77/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	3/231/0	1/77/0	-	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	3/2400/0	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	(1)	-	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	3000 Volts	(1)	-	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	_	(1)	3/9/0	1/6/0	1/6/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	Pass	Pass	Pass

- QBS: Qual By Similarity
- Qual Device TPS51397ARJER is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Notes;
  - (1) TPS51397ARJE uses the same core silicon and package as TPS56C230RJE  $\,$

Quality and Environmental data is available at Ti's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2303-022

### Qualification Results

### Data Displayed as: Number of lots / Total sample size / Total failed

Туре		Test Name	Condition	Duration	Qual Device: TPS65992DBFREFR	Qual Device: TPS65992DBFREFR	Qual Device: TPS65991BFRSMR	Qual Device: TPS65992SBFRSMR	QBS Reference: TPS61378QWRTERQ1	QBS Reference: PTPS65992SAOCRSMR PTPS65992ADRSMR	QBS Reference: PTPS65992DADRJKR	QBS Reference: TPS65992DADRJKR
HAST	A2	Blased HAST	110C/85%RH	264 Hours						1/77/0	2/154/0	
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	-	-
UHAST	А3	Autoclave	121C/15psig	96 Hours						1/77/0	2/154/0	
UHAST	АЗ	Unbiased HAST	130C/85%RH	96 Hours					3/231/0			
тс	A4	Temperature Cycle	-65C/150C	500 Cycles					3/231/0	1/77/0	2/154/0	1/77/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	1/77/0	2/154/11	-
HTSL	Α6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	3/135/0	-		
HTOL	81	Life Test	125C	1000 Hours	-	-	-	-	-	3/231/0	-	1/77/0
HTOL	81	Life Test	150C	408 Hours					3/231/0			
ELFR	В2	Early Life Failure Rate	125C	48 Hours					3/2400/0	3/2400/0		
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-				1/15/0			

SD	СЗ	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/-15 minutes); PB Solder;								2/44/0	
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)						1/15/0			
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/-15 minutes); PB- Free Solder;								2/44/0	
PD	C4	Physical Dimensions	Cpk>1.67						3/30/0			
ESD	E2	ESD CDM	-	1000 Volts					1/3/0			1/3/0
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	-	1/3/0	1/3/0	-
ESD	E2	ESD HBM		1500 Volts						1/3/0		
ESD	E2	ESD HBM		2500 Volts								1/3/0
ESD	E2	ESD HBM		3000 Volts					1/3/0			
ESD	E2	ESD HBM		4000 Volts							1/3/0	
LU	E4	Latch-Up	Per JESD78		-	-		-	1/6/0	1/3/0	1/6/0	1/6/0
CHAR	ES	Electrical Characterization	Per Datasheet Parameters		1/30/0	1/30/0		1/30/0			-	1/30/0
CHAR	ES	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0		-	
FTY	E6	Final Test Yield			1/1/0	1/1/0	1/1/0	1/1/0				

- OBS: Qual By Similarity
  Qual Device TP5659920BFREFR is qualified at MSL2 260C.
  Qual Device TP56599920BFREFR is qualified at MSL2 260C.
  Qual Device TP56599925BFR is qualified at MSL2 260C.
  Qual Device TP56599285BFR is qualified at MSL2 260C.
  Qual Device TP5659928BFRM is qualified at MSL2 260C.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/200 Hours, and 155C/240 Hours
  The following are equivalent HTSL options based on an activation energy of 0.7eV: 130C/1k Hours, and 170C/220 Hours
  The following are equivalent Temp Cycle options per JESO47: -55C/125C/700 Cycles and -65C/130C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2212-027

[1]-Lost or Damaged - Not Tested

# **Qualification Results**

# Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Condition	Duration	QBS Process Reference: PCM6260QRTVRQ1	QBS Process Reference: <u>TPS51486RJER</u>	QBS Product Reference: PTPS65994AAYBGR	QBS Product Reference: PTPS65994AAYBGR	QBS Product Reference: TPS65994ACYBGR	QBS Product Reference: <u>TPS65994ACYBGR</u>
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	1/77/0	2/154/0
UHAST	А3	Unbiased HAST	130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	1/77/0	2/154/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	-	3/231/0	1/77/0	1/77/0	2/154/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	3/231/0	1/77/0	1/77/0	2/154/0
HTOL	B1	Life Test	125C	1000 Hours	3/231/0	3/231/0	1/77/0	-	1/77/0	2/154/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	3/2400/0	3/2400/0	-	-	-	-
PD	C4	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	1/3/0	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	1/6/0	1/3/0	-	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/Pass	1/Pass	-	-
FTY	E6	Final Test Yield	-	-	-	-	-	-	-	-

- . Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- . The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

TI Qualification ID: R-NPD-2207-096

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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